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[Diodes Incorporated](#)
[DMN2004K-7](#)

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DMN2004K

N-CHANNEL ENHANCEMENT MODE MOSFET

Product Summary

V _{(BR)DSS}	R _{DS(ON)}	I _D T _A = +25°C
20V	0.55Ω @ V _{GS} = 4.5V	630mA
	0.9Ω @ V _{GS} = 1.8V	410mA

Description

This new generation MOSFET has been designed to minimize the on-state resistance (R_{DS(ON)}) and yet maintain superior switching performance, making it ideal for high efficiency power management applications.

Applications

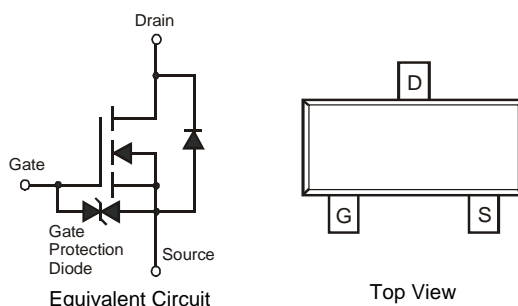
- DC-DC Converters
- Power Management Functions

Features and Benefits

- Low On-Resistance: R_{DS(ON)} = 550_(max)mΩ @ V_{GS} = 4.5V
- Low Gate Threshold Voltage
- Low Input Capacitance
- Fast Switching Speed
- Low Input/Output Leakage
- ESD Protected up to 2KV
- **Totally Lead-Free & Fully RoHS Compliant (Notes 1 & 2)**
- **Halogen and Antimony Free. "Green" Device (Note 3)**
- **Qualified to AEC-Q101 standards for High Reliability**

Mechanical Data

- Case: SOT23
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
- Terminals: Finish — Matte Tin annealed over Alloy 42 leadframe. Solderable per MIL-STD-202, Method 208 Ⓔ3
- Terminal Connections: See Diagram
- Weight: 0.008 grams (approximate)

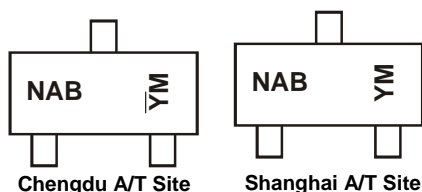


Ordering Information (Note 4)

Part Number	Case	Packaging
DMN2004K-7	SOT23	3000/Tape & Reel

- Notes:
1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.
 2. See http://www.diodes.com/quality/lead_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.
 3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.
 4. For packaging details, go to our website at <http://www.diodes.com/products/packages.html>.

Marking Information



NAB = Product Type Marking Code
 YM = Date Code Marking for SAT (Shanghai Assembly/ Test site)
 YM = Date Code Marking for CAT (Chengdu Assembly/ Test site)
 Y or Ȳ = Year (ex: A = 2013)
 M = Month (ex: 9 = September)

Date Code Key

Year Code	2008	2009	2010	2011	2012	2013	2014	2015
Code	V	W	X	Y	Z	A	B	C

Month Code	Jan	Feb	Mar	Apr	May	Jun	Jul	Aug	Sep	Oct	Nov	Dec
Code	1	2	3	4	5	6	7	8	9	O	N	D

Maximum Ratings (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Drain-Source Voltage	V_{DSS}	20	V
Gate-Source Voltage	V_{GSS}	± 8	V
Drain Current (Note 5) $V_{GS} = 4.5\text{V}$	I_D	630	mA
Steady State $T_A = +25^\circ\text{C}$ $T_A = +85^\circ\text{C}$		450	
Drain Current (Note 5) $V_{GS} = 1.8\text{V}$	I_D	410	mA
Steady State $T_A = +25^\circ\text{C}$ $T_A = +85^\circ\text{C}$		300	
Pulsed Drain Current (Note 6)	I_{DM}	1.5	A

Thermal Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Value	Units
Total Power Dissipation (Note 5)	P_D	350	mW
Thermal Resistance, Junction to Ambient	$R_{\theta JA}$	357	$^\circ\text{C}/\text{W}$
Operating and Storage Temperature Range	T_J, T_{STG}	-65 to +150	$^\circ\text{C}$

Electrical Characteristics (@ $T_A = +25^\circ\text{C}$, unless otherwise specified.)

Characteristic	Symbol	Min	Typ	Max	Unit	Test Condition
OFF CHARACTERISTICS (Note 7)						
Drain-Source Breakdown Voltage	BV_{DSS}	20	—	—	V	$V_{GS} = 0\text{V}, I_D = 10\mu\text{A}$
Zero Gate Voltage Drain Current	I_{DSS}	—	—	1	μA	$V_{DS} = 16\text{V}, V_{GS} = 0\text{V}$
Gate-Source Leakage	I_{GSS}	—	—	± 1	μA	$V_{GS} = \pm 4.5\text{V}, V_{DS} = 0\text{V}$
ON CHARACTERISTICS (Note 7)						
Gate Threshold Voltage	$V_{GS(th)}$	0.5	—	1.0	V	$V_{DS} = V_{GS}, I_D = 250\mu\text{A}$
Static Drain-Source On-Resistance	$R_{DS(on)}$	—	0.4	0.55	Ω	$V_{GS} = 4.5\text{V}, I_D = 540\text{mA}$
			0.5	0.70		$V_{GS} = 2.5\text{V}, I_D = 500\text{mA}$
			0.7	0.9		$V_{GS} = 1.8\text{V}, I_D = 350\text{mA}$
						$V_{GS} = 1.8\text{V}, I_D = 350\text{mA}$
Forward Transfer Admittance	$ Y_{fs} $	200	—	—	ms	$V_{DS} = 10\text{V}, I_D = 0.2\text{A}$
Source Current	I_S	—	—	0.5	A	—
Diode Forward Voltage (Note 7)	V_{SD}	0.6	—	1	V	$V_{GS} = 0\text{V}, I_S = 500\text{mA}$
DYNAMIC CHARACTERISTICS						
Input Capacitance	C_{iss}	—	—	150	pF	$V_{DS} = 16\text{V}, V_{GS} = 0\text{V}$ $f = 1.0\text{MHz}$
Output Capacitance	C_{oss}	—	—	25	pF	
Reverse Transfer Capacitance	C_{rss}	—	—	20	pF	
Gate Resistance	R_g	—	292	—	Ω	$V_{DS} = 0\text{V}, V_{GS} = 0\text{V}, f = 1.0\text{MHz}$
Total Gate Charge	Q_g	—	0.9	—	nC	$V_{DS} = 15\text{V}, V_{GS} = 4.5\text{V}, I_D = 0.5\text{A}$
Gate-Source Charge	Q_{gs}	—	0.2	—		
Gate-Drain Charge	Q_{gd}	—	0.2	—		
Turn-On Delay Time	$t_{D(on)}$	—	5.7	—	ns	$V_{GS} = 8\text{V}, V_{DS} = 15\text{V},$ $R_G = 6\Omega, R_L = 30\Omega$
Turn-On Rise Time	t_r	—	8.4	—		
Turn-Off Delay Time	$t_{D(off)}$	—	59.4	—		
Turn-Off Fall Time	t_f	—	37.6	—		
Body Diode Reverse Recovery Time	t_{rr}	—	5.5	—	ns	$I_S = 0.5\text{A}, dI/dt = -100\text{A}/\mu\text{s}$
Body Diode Reverse Recovery Charge	Q_{rr}	—	0.85	—	nC	$I_S = 0.5\text{A}, dI/dt = -100\text{A}/\mu\text{s}$

- Notes: 5. Device mounted on FR-4 PCB, with minimum recommended pad layout, single sided.
 6. Pulse width $\leq 10\mu\text{s}$, Duty Cycle $\leq 1\%$.
 7. Short duration pulse test used to minimize self-heating effect.



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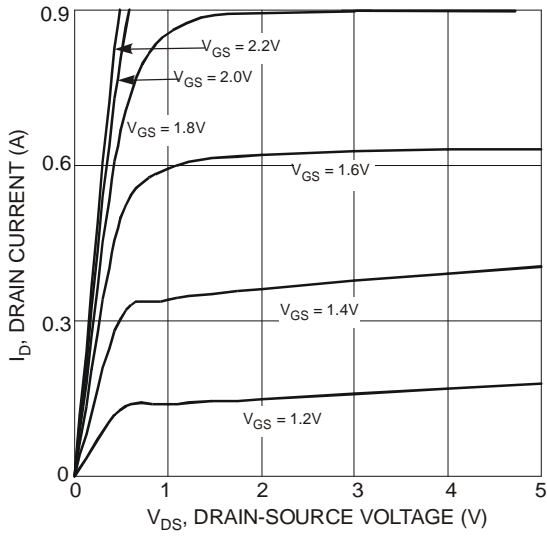


Figure 1 Typical Output Characteristics

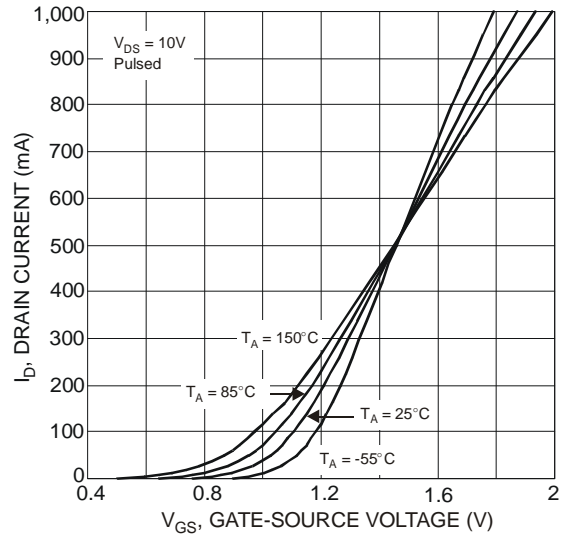


Figure 2 Reverse Drain Current vs. Source-Drain Voltage

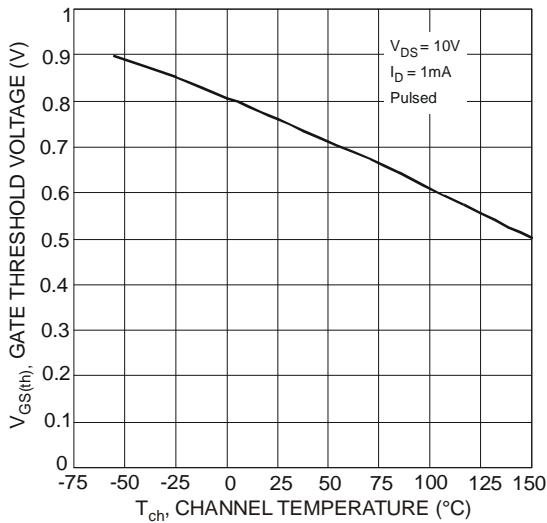


Figure 3 Gate Threshold Voltage vs. Channel Temperature

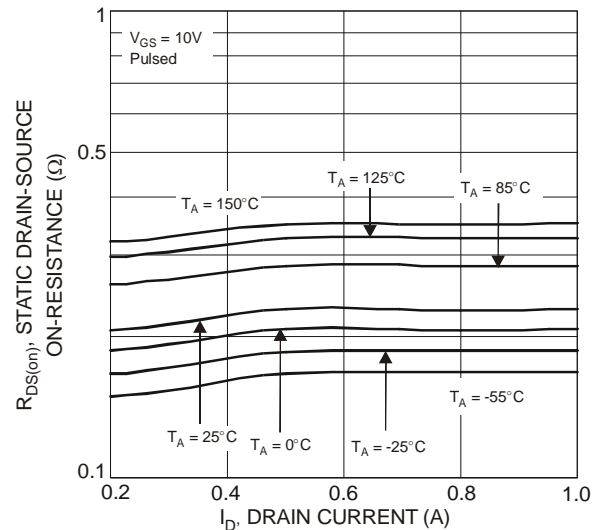


Figure 4 Static Drain-Source On-Resistance vs. Drain Current

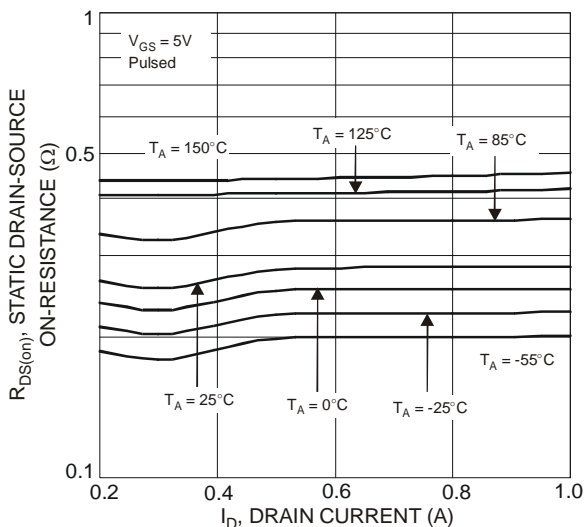


Figure 5 Static Drain-Source On-Resistance vs. Drain Current

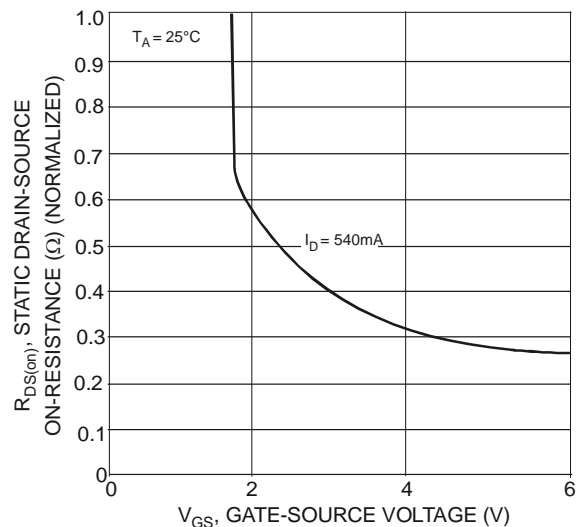


Figure 6 Static Drain-Source, On-Resistance vs. Gate-Source Voltage



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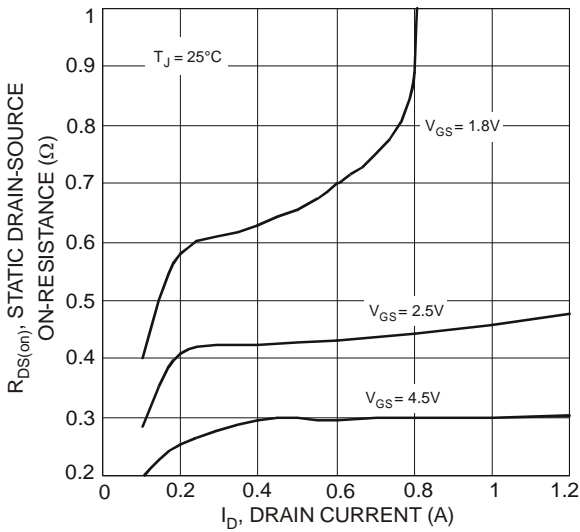


Figure 7 On-Resistance vs. Drain Current and Gate Voltage

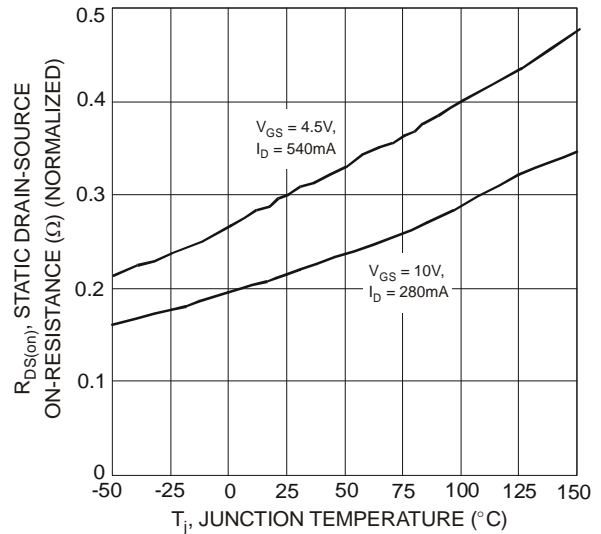


Figure 8 Static Drain-Source, On-Resistance vs. Temperature

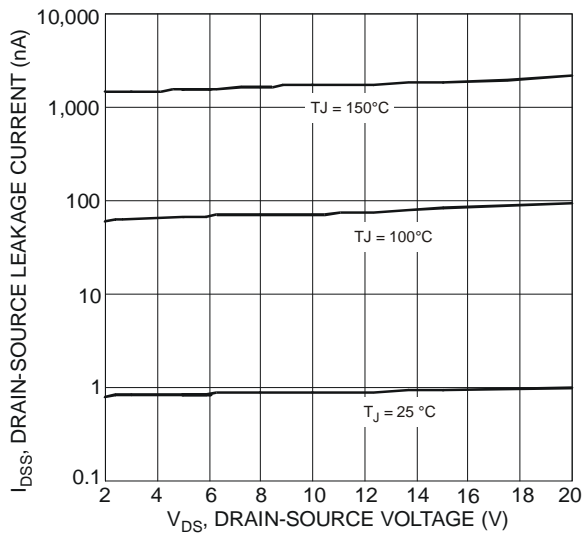


Figure 9 Drain Source Leakage Current vs. Voltage

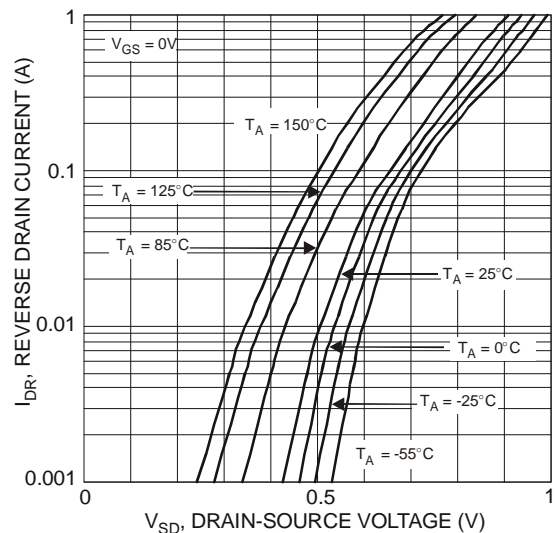


Figure 10 Reverse Drain Current vs. Source-Drain Voltage

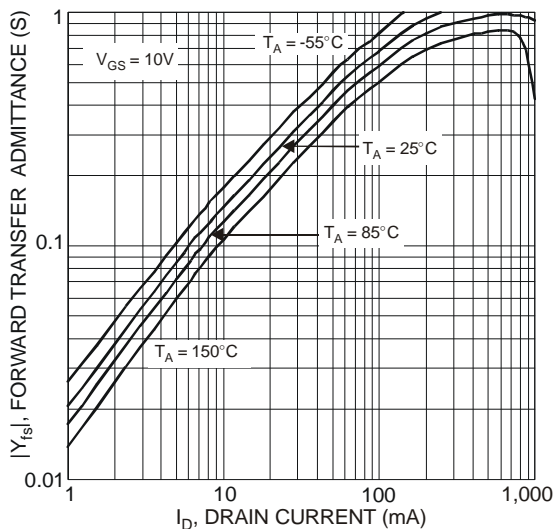


Figure 11 Forward Transfer Admittance vs. Drain Current

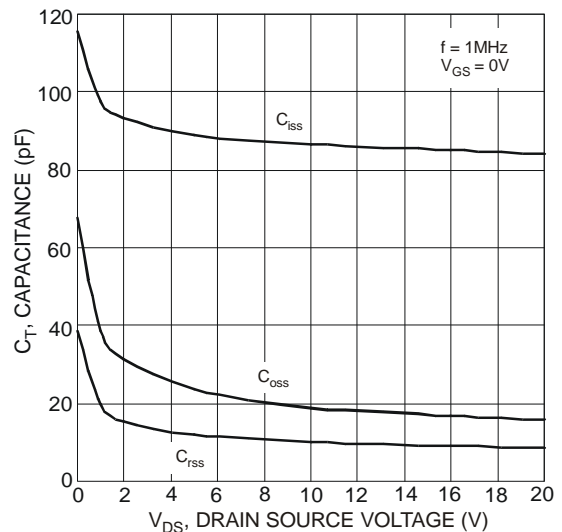


Figure 12 Capacitance Variation

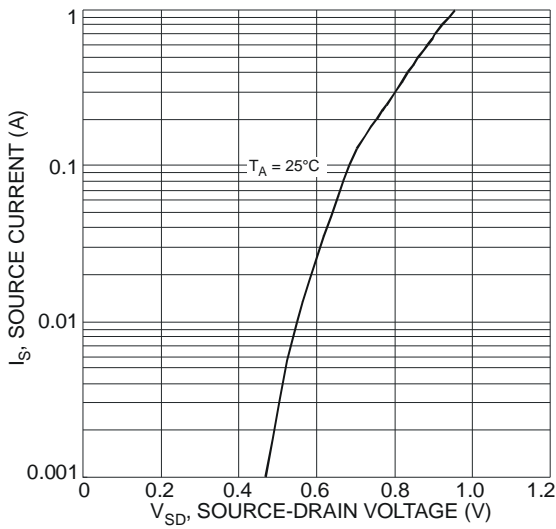


Figure 13 Diode Forward Voltage vs. Current

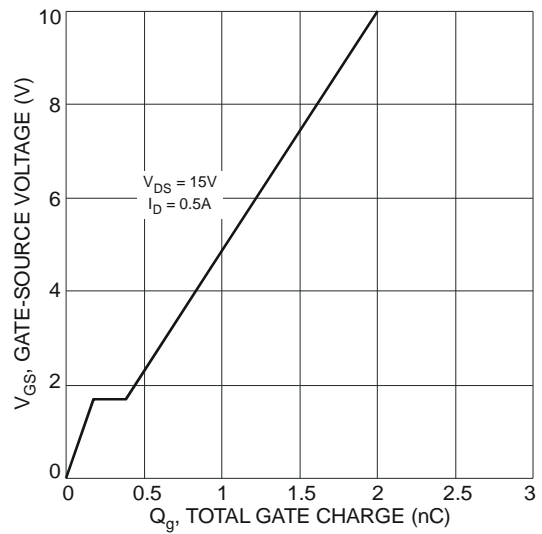
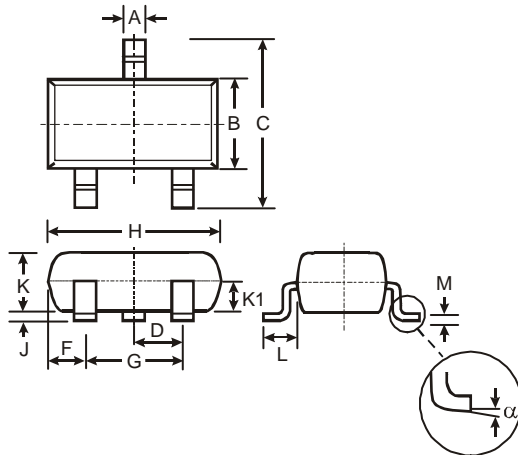


Figure 14 Gate-Charge Characteristics

Package Outline Dimensions

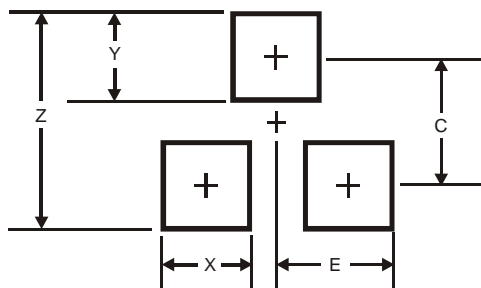
Please see AP02002 at <http://www.diodes.com/datasheets/ap02002.pdf> for latest version.



SOT23			
Dim	Min	Max	Typ
A	0.37	0.51	0.40
B	1.20	1.40	1.30
C	2.30	2.50	2.40
D	0.89	1.03	0.915
F	0.45	0.60	0.535
G	1.78	2.05	1.83
H	2.80	3.00	2.90
J	0.013	0.10	0.05
K	0.903	1.10	1.00
K1	-	-	0.400
L	0.45	0.61	0.55
M	0.085	0.18	0.11
α	0°	8°	-
All Dimensions in mm			

Suggested Pad Layout

Please see AP02001 at <http://www.diodes.com/datasheets/ap02001.pdf> for latest version.



Dimensions	Value (in mm)
Z	2.9
X	0.8
Y	0.9
C	2.0
E	1.35

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